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Atty. Docket No.: 9862-000333/US

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	U8-28-2009 <u> </u>
To the Honor Please record	103572170 thereof.
Name of conveying party(ies):	2. Name and address of receiving party(ies)
Yun-Seok CHOI	Name: Samsung Electronics Co., Ltd.
Hee-Seok LEE	Street Address: 416, Maetan-dong, Yeongtong-gu
Kyoung-Sei CHOI	City: Suwon-si State: Gyeonggi-do
Additional name(s) of conveying party(ies) attached?	Country: Republic of Korea
3. Nature of conveyance:	
□ Assignment □ Merger □ Security Agreen	nent Additional name(s) & address(es) attached? YES NO
☐ Change of Name ☐ Other:	
Execution Date: August 10, 2009; August 10, 2 August 10, 2009	2009;
4. Application number(s) or patent number(s): If this document is being filed together wi	th a new application, the execution date of the application is:
A. Patent Application No(s).	B. Patent No.(s).
Additional numbers of party to whom correspondence concerning document should be mailed: Name: HARNESS, DICKEY & PIERCE, P.L.C. Street Address: P.O. BOX 8910 City: RESTON State: VA ZIP: 20195 Country: USA	bers attached? YES NO 6. Total No. of applications/patents involved: One (1) 7. Total fee (37 C.F.R. § 3.41): \$40.00 Enclosed Authorized to be charged to deposit account, if no fee attached. 8. Deposit account number: 08-0750
	(Attach triplicate copy of this page if paying by deposit account)
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9. Statement and signature.	
To the best of my knowledge and belief, the for copy of the original document. John A. Castellano, Reg. No. 35,094 Name of Person Signing/Reg. No.	Signature regoing information is true and correct and any attached copy is a true August 19, 2009 Date
Total number of pages include	ding cover sheet, attachments, and document: 3
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REEL: 023152 FRAME: 0765

ASSIGNMENT

WHEREAS, the undersigned, hereinafter referred to collectively as Assignor, has invented:

FLIP CHIP PACKAGES AND METHODS OF MANUFACTURING THE SAME

for which Assignor is about to make or has made United States or International application for patent

(a)	Ø	executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney);
(b)		executed on,; or
(c)		filed on, and assigned Serial No or PCT International

WHEREAS, Samsung Electronics Co., Ltd., 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as Assignee, is desirous of acquiring all right, title, and interest therein:

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof is hereby acknowledged, Assignor agrees to, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the invention as described in the aforesaid application and all United States Letters Patent which may be granted therefore, and all divisions, continuations, relssues, reexaminations and extensions thereof, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications or patents resulting therefrom;

Assignor hereby covenants and agrees to execute all Instruments or documents required or requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or Inventor's Certificate to Assignee.

The undersigned hereby grant(s) the law firm of Harness, Dickey & Pierce, P.L.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

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ASSIGNMENT

Dated

Hee-Seok LEE

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